

ABSTRACT OF THE DISCLOSURE

There are included the steps of preparing a wiring substrate having a wiring pattern on a surface, bonding a connection terminal of electronic chip, which has a predetermined element and the connection terminal on one surface, to the wiring pattern of the wiring substrate by a flip-chip bonding, forming an insulating film on the wiring substrate to have a film thickness that covers the electronic chip, or a film thickness that exposes at least another surface of the electronic chip, and reducing a thickness of the electronic chip by grinding another surface of the electronic chip and the insulating film.